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With the principle of "Quality Parts, Customers Priority, Honest Operation, and Considerate Service", our business mainly focus on the distribution of electronic components. Line cards we deal with include Microchip, ALPS, ROHM, Xilinx, Pulse, ON, Everlight and Freescale. Main products comprise IC, Modules, Potentiometer, IC Socket, Relay, Connector. Our parts cover such applications as commercial, industrial, and automotives areas.

We are looking forward to setting up business relationship with you and hope to provide you with the best service and solution. Let us make a better world for our industry!



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DATASHEET

Technical Data Sheet
1.9mm Round Subminiature Axial Phototransistor
EAPST2520A1

Features

- Fast response time
- High photo sensitivity
- Small junction capacitance
- Compatible with infrared and vapor phase reflow solder process.
- Pb free
- RoHS Compliance
- The product itself will remain within RoHS compliant version.
- Compliance with EU REACH.
- Compliance Halogen Free .(Br <900 ppm ,Cl <900 ppm , Br+Cl < 1500 ppm)

Description

• EAPST2520A1 is a phototransistor in miniature SMD package which is molded in water clear plastic with spherical top view lens. The device is spectrally matched to infrared emitting diode.

Applications

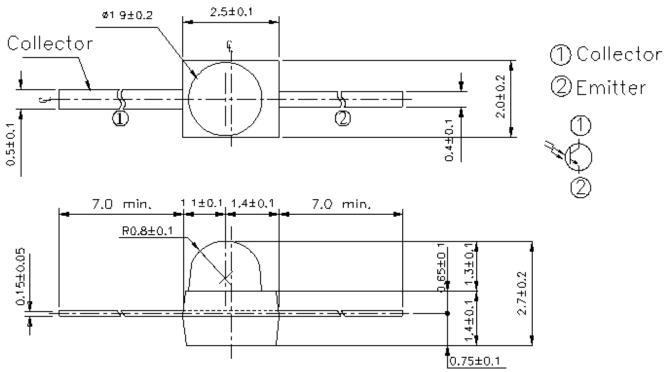
- Miniature switch
- Counters and sorter
- Position sensor
- Infrared applied system

Device Selection Guide

Device No.	Chip Material	Lens Color	
EAPST2520A1	Silicon	Black	



Package Dimensions



Notes: 1.All dimensions are in millimeters

2.Tolerances unless dimensions ±0.1mm

Absolute Maximum Ratings (Ta=25°C)

Parameter	Symbol	Rating	Unit
Collector-Emitter Voltage	V_{CEO}	30	V
Emitter-Collector-Voltage	V_{ECO}	5	V
Collector Current	I_{C}	20	mA
Operating Temperature	Topr	-25 ~ +85	$^{\circ}\!\mathbb{C}$
Storage Temperature	T_{stg}	-40 ~ +100	$^{\circ}\!\mathbb{C}$
Soldering Temperature *1	T _{sol}	260	$^{\circ}\!\mathbb{C}$
Power Dissipation at(or below) 25°C Free Air Temperature	P _c	75	mW

Notes: *1:Soldering time ≤ 5 seconds.

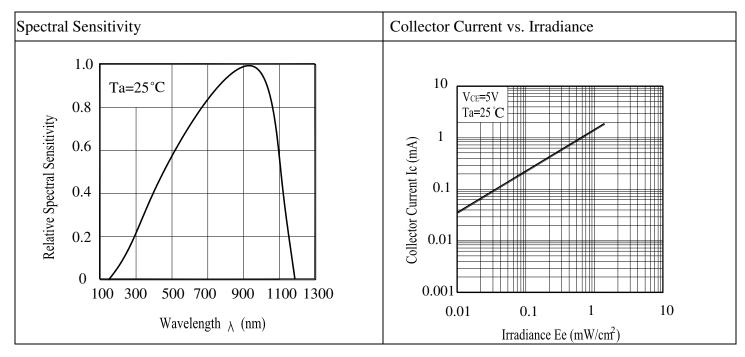


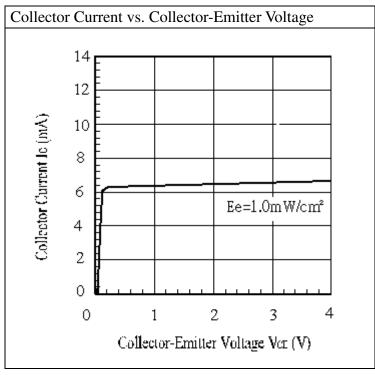
Electro-Optical Characteristics (Ta=25°C)

Parameter	Symbol	Min.	Тур.	Max.	Unit	Condition
Rang Of Spectral Bandwidth	λ 0.5	400		1100	nm	
Wavelength Of Peak Sensitivity	λ _P		940		nm	
Collector-Emitter Breakdown Voltage	BV _{CEO}	30			V	I _C =100µ A Ee=0mW/cm ²
Emitter-Collector Breakdown Voltage	BV_{ECO}	5			V	$I_E=100\mu$ A Ee=0mW/cm ²
Collector-Emitter Saturation Voltage	V _{CE(sat)}			0.4	V	$I_C=2mA$ Ee=1m W/cm ²
Collector Dark Current	I_{CEO}			100	nA	V _{CE} =20V Ee=0mW/cm ²
On State Collector Current	$I_{C(ON)}$	1.0	1.5		mA	V _{CE} =5V Ee=1mW/cm ²
Rise Time	$t_{\rm r}$		15		5	V _{CE} =5V I _C =1mA
Fall Time	t_{f}		15		μS	$R_L=1000\Omega$



Typical Electrical/Optical/Characteristics Curves







Precautions For Use

1. Over-current-proof

Customer must apply resistors for protection, otherwise slight voltage shift will cause big current change (Burn out will happen).

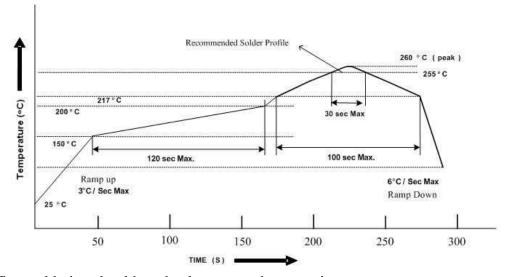
2. Storage

- 2.1 Do not open moisture proof bag before the products are ready to use.
- 2.2 Before opening the package, the LEDs should be kept at 30°C or less and 90%RH or less.
- 2.3 The LEDs should be used within a year.
- 2.4 After opening the package, the LEDs should be kept at 30° C or less and 60%RH or less.
- 2.5 The LEDs should be used within 168 hours (7 days) after opening the package.
- 2.6 If the moisture absorbent material (silica gel) has faded away or the LEDs have exceeded the storage time, baking treatment should be performed using the following conditions.

Baking treatment : $60\pm5^{\circ}$ C for Min 24 hours.

3. Soldering Condition

3.1 Pb-free solder temperature profile



- 3.2 Reflow soldering should not be done more than two times.
- 3.3 When soldering, do not put stress on the LEDs during heating.
- 3.4 After soldering, do not warp the circuit board.

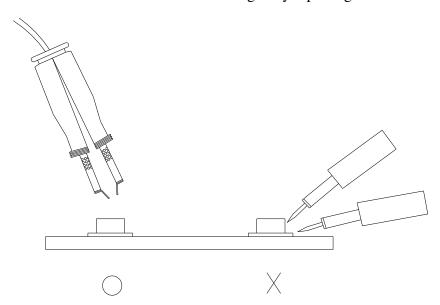


4. Soldering Iron

Each terminal is to go to the tip of soldering iron temperature less than 350°C for 3 seconds within once in less than the soldering iron capacity 25W. Leave two seconds and more intervals, and do soldering of each terminal. Be careful because the damage of the product is often started at the time of the hand solder.

5. Repairing

Repair should not be done after the LEDs have been soldered. When repairing is unavoidable, a double-head soldering iron should be used (as below figure). It should be confirmed beforehand whether the characteristics of the LEDs will or will not be damaged by repairing.

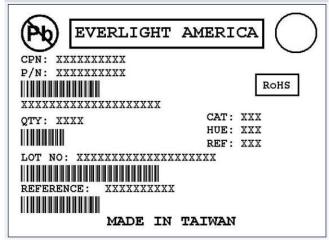




Packing Quantity Specification

1000PCS/1Bag

Label Form Specification



CPN: Customer's Production Number

P/N : Production Number QTY: Packing Quantity

CAT: Ranks

HUE: Peak Wavelength

REF: Reference

LOT No: Lot Number

MADE IN TAIWAN: Production Place

Notes

- 1. Above specification may be changed without notice. Everlight Americas will reserve authority on material change for above specification.
- 2. When using this product, please observe the absolute maximum ratings and the instructions for using outlined in these specification sheets. Everlight Americas assumes no responsibility for any damage resulting from use of the product which does not comply with the absolute maximum ratings and the instructions included in these specification sheets.
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